## *AMENDMENTS TO THE CLAIMS*

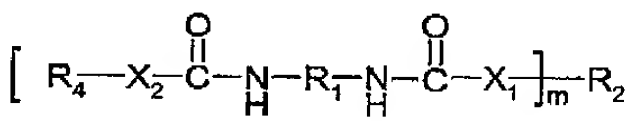
Please amend the claims as indicated hereafter.

***Claims:***

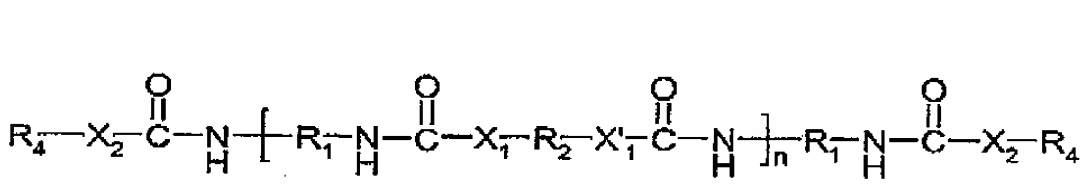
1-14.(Previously canceled).

15. (Amended) A method of joining electrically conductive materials~~, which comprises~~ comprising the step of applying an adhesive composition ~~to said materials to provide a stable electrical contact resistance comprising~~ consisting of:

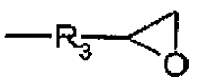
an epoxide-modified polyurethane resin having the following structure



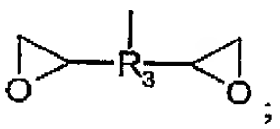
or



where m is 2 or 3; n is one or greater; $R_1$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; $R_2$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; $R_4$ is either:



or



;

$R_3$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and $X_1$ and $X_2$ are either a single bond, –O–; –COO–; –NH–; or –S–; wherein the cross-linking agent is a carboxylic acid anhydride cross-linker;

a cross-linking agent;

an adhesion promoter ~~in an amount sufficient for promoting adhesion of the adhesive to a substrate~~; and

a conductive filler.

16. (Canceled)

17. (Canceled)

18. (Presently amended) The method of Claim ~~16~~ 15, wherein the electrically conductive materials are present on a printed circuit board.

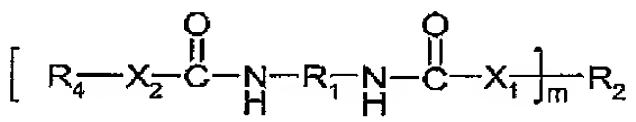
19.-20. (Canceled).

21.-29. (Canceled)

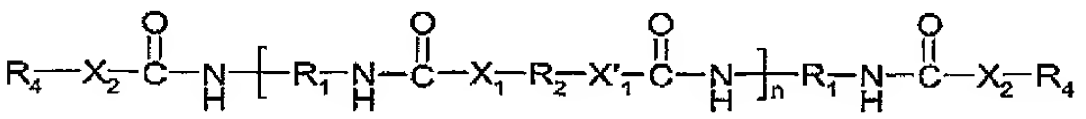
30. (Presently amended) A method of joining electrically conductive materials, comprising:

applying an electrically conductive adhesive composition to at least one of said electrically conductive materials, wherein said electrically conductive adhesive composition ~~comprises~~ consists of an epoxide-modified polyurethane resin, a cross-linking agent, an adhesion promoter, and a conductive filler,

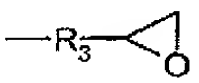
wherein said epoxide-modified polyurethane resin has the following structure:



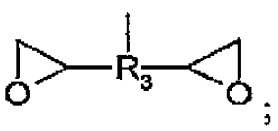
or



where m is 2 or 3; n is one or greater; $R_1$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an aromatic hydrocarbon radical, or an araliphatic hydrocarbon radical; $R_2$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester; or a polyether; $R_4$ is either:



or



;

$R_3$ is an aliphatic hydrocarbon radical, a cycloaliphatic hydrocarbon radical, an alkoxy radical, a polyester, or a polyether; and $X_1$ and $X_2$ are either a single bond, –O–; –COO–; –NH–; or –S–.

31. (Previously presented) The method of claim 30 wherein said electrically conductive materials are at least one of the following; a chip and a printed circuit board.

32. (Canceled)

33. (Previously added) The method of claim 15, wherein the adhesion promoter is selected from the group consisting of alkylchlorosilanes, dialkyldichlorosilanes, alkyltrichlorosilanes; organosilane esters; vinylsilanes; aminoalkylsilanes; diaminoalkylsilanes; styrylaminosilanes; ureidoalkylsilane esters; alkoxysilanes; acryloxyalkylsilane esters; methacryloxyalkylsilane esters; and mercaptoalkylsilane esters, and combinations thereof.

34. (Previously added) The method of claim 15, wherein the adhesion promoter is (3-glycidoxypropyl)trimethoxysilane.